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Attorney Docket No. 108298746US  
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PTO/SB/08a/b (08-03)

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Substitute for form 1449A/B/PTO				Complete If Known	
				Application Number	10/723,363
				Filing Date	November 26, 2003
				First Named Inventor	Mark E. Tuttle
				Art Unit	2624 2624
				Examiner Name	Not Yet Assigned Amara Abdi
Sheet	1	of	1	Attorney Docket Number	108298746US

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code <sup>2</sup> (if known)			
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. <sup>1</sup>Applicant's unique citation designation number (optional). <sup>2</sup>See Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language Translation is attached.

NON PATENT LITERATURE DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.			T <sup>2</sup>
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				Art Unit	2021 2624
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Sheet	3	of	6	Attorney Docket Number	108298746US

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NON PATENT LITERATURE DOCUMENTS					
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Substitute for form 1449A/B/PTO				Complete If Known	
				Application Number	10/723,363-Conf. #9952
				Filing Date	November 26, 2003
				First Named Inventor	Mark E. Tuttle
				Art Unit	26242624
				Examiner Name	Not Yet Assigned Amara Abdi
Sheet	6	of	6	Attorney Docket Number	108298746US

/A.A./	YOSHIDA, J. "TransChip rolls out a single-chip CMOS imager," 3 pages, EE Times, July 18, 2003.	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup>Applicant's unique citation designation number (optional). <sup>2</sup>Applicant is to place a check mark here if English language Translation is attached.

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